



1 / 5

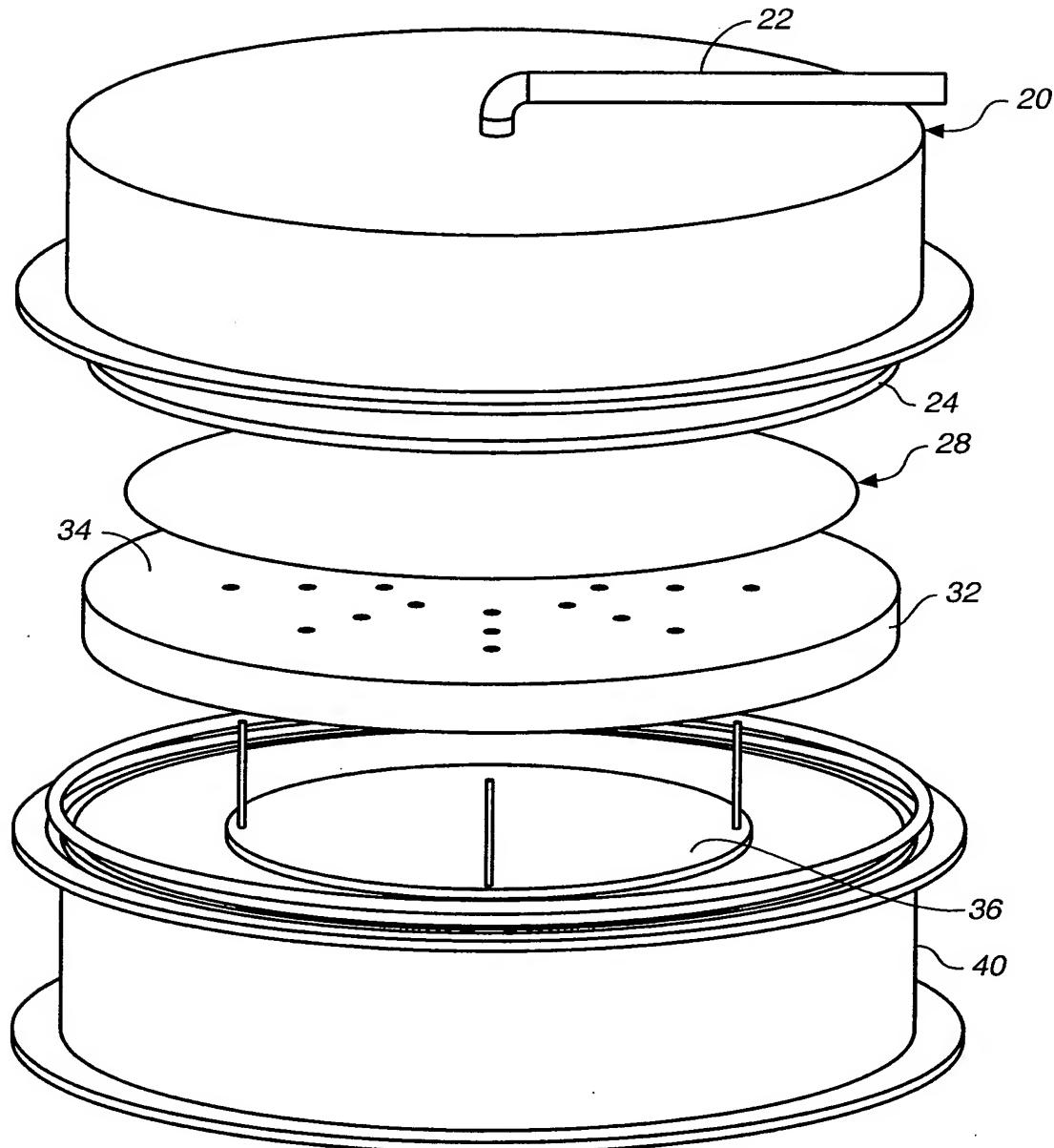


FIG._1
(PRIOR ART)



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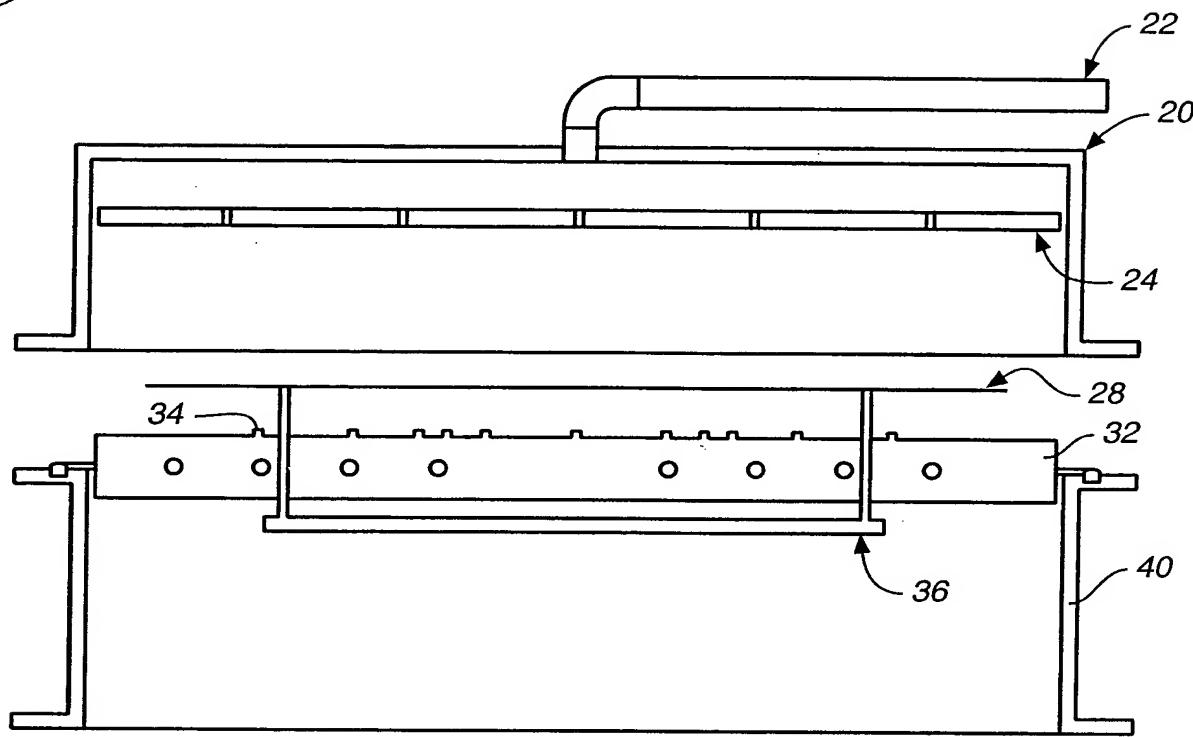


FIG. 2 (PRIOR ART)

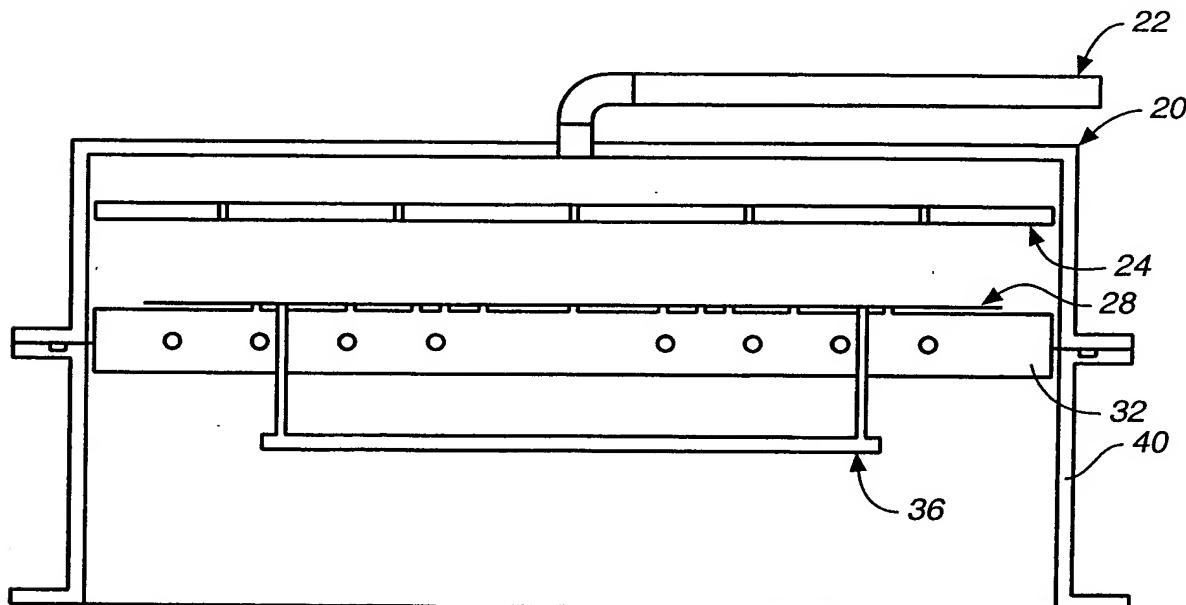


FIG. 3 (PRIOR ART)



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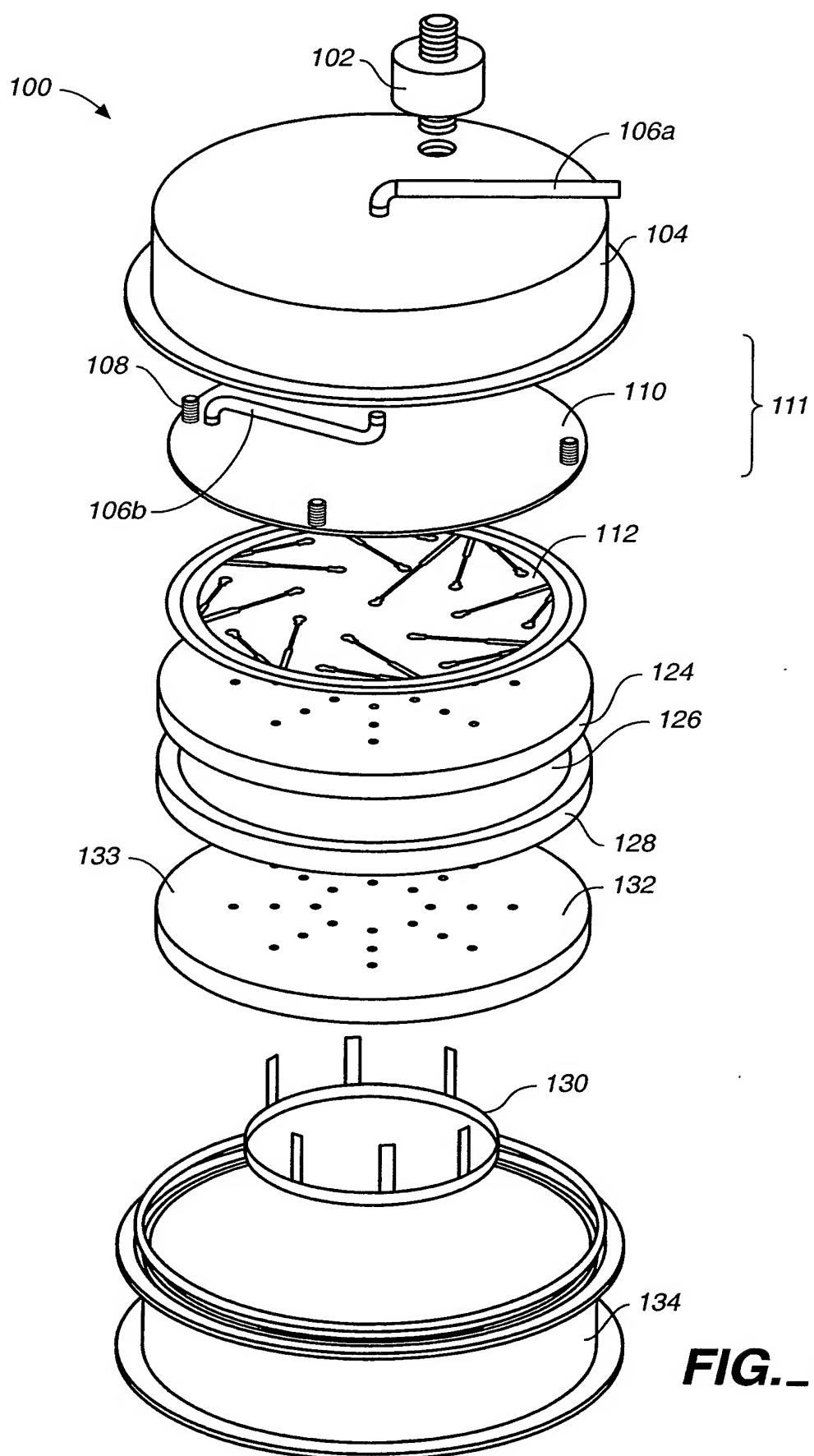


FIG._4

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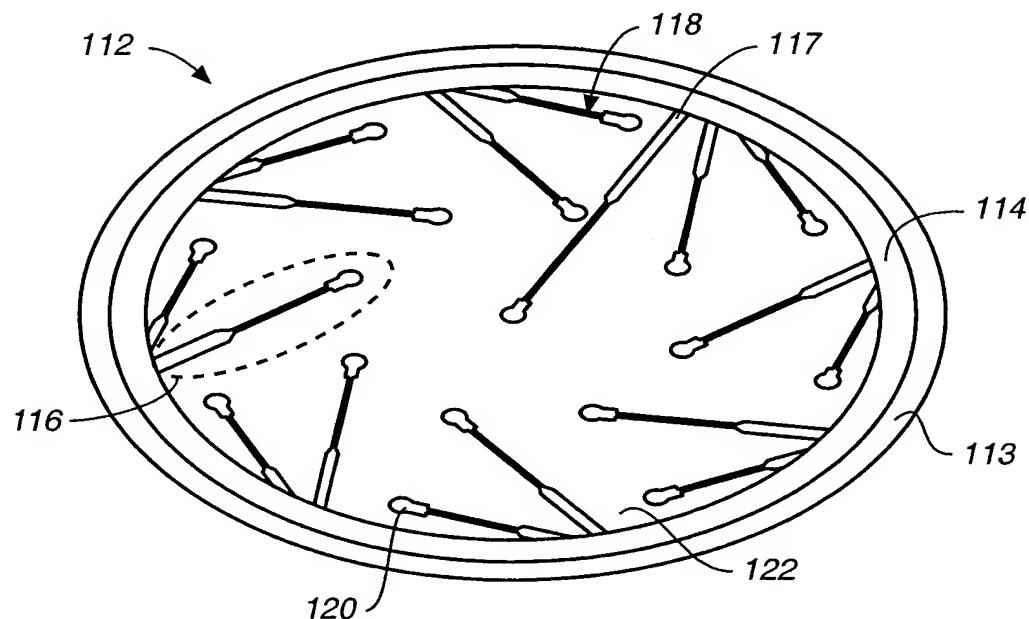


FIG. 5

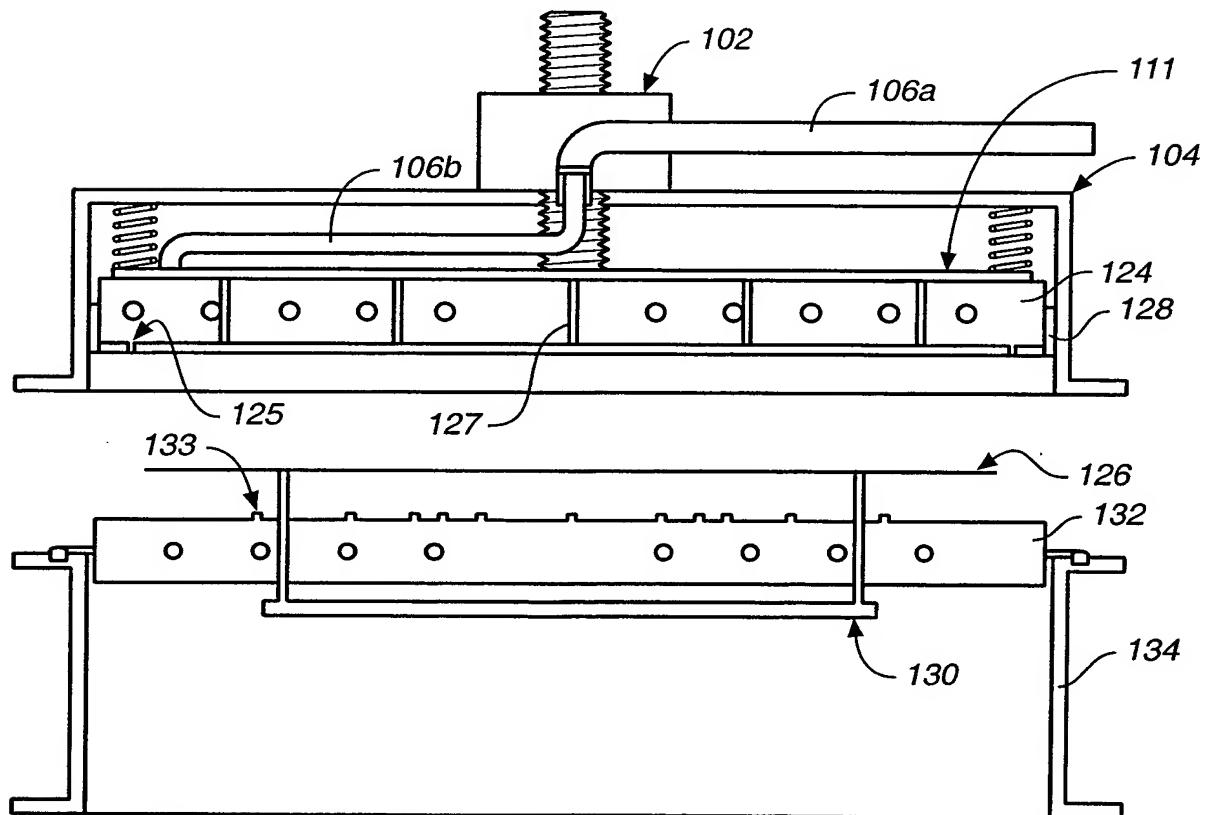
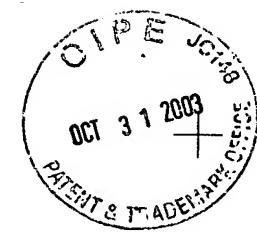


FIG. 6



Appn. No.: Unassigned Docket No.: SENS.007US1
Title: System and Method for Heating and Cooling Wafer....
Inventors: Wayne Glenn Renken Exp. Mail: EU9626454525U
Filing Date: Herewith Atty. Tel: (415) 318-1160 Sheet 5 of 5

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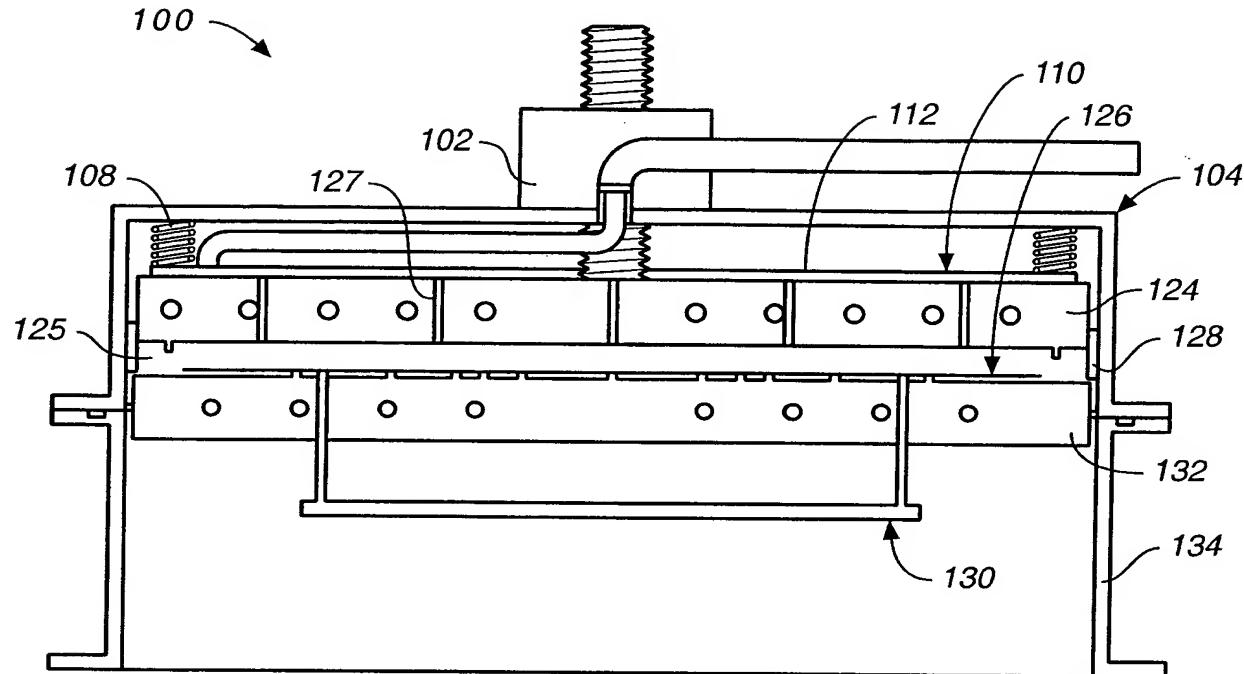


FIG._7

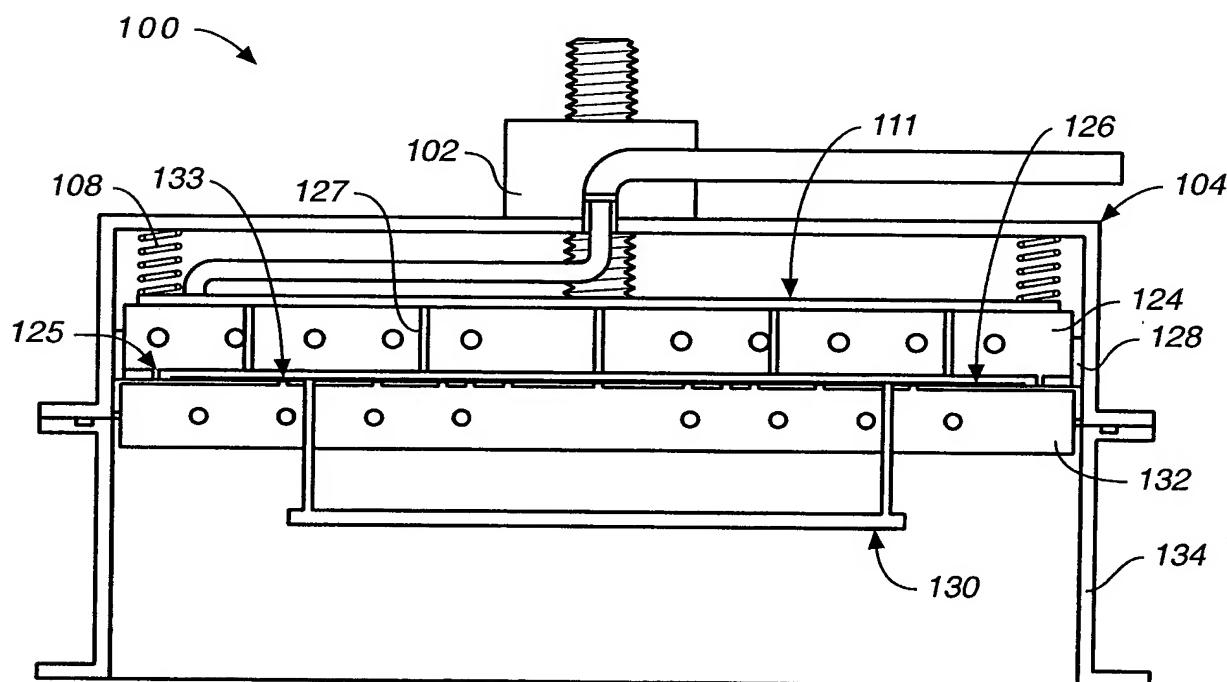


FIG._8